AMENDMENT TO THE CLAIMS:

This listing of claims will replace all prior versions of claims in the application:

LISTING OF CLAIMS:

1. (CURRENTLY AMENDED) A method of creating a conductive path between two or more conductive layers, wherein the conductive layers are separated by one or more dielectric layers, the method comprising:
~~exposing portions of at least two conductive layers;~~
applying a conductive material to ~~the~~ exposed portions of ~~the~~ at least two conductive layers, the conductive material creating an electrical coupling between the conductive layers; and
grounding at least one of the conductive layers to a controlled ground potential.

2. (ORIGINAL) A method as recited in claim 1, wherein the portions of the conductive layers are exposed by recessing at least one of the conductive layers and any dielectric layers positioned between the conductive layers, the conductive material overhanging an uppermost of the conductive layers.

3. (ORIGINAL) A method as recited in claim 2, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

4. (CURRENTLY AMENDED) A method as recited in claim 2, wherein the conductive material is ~~selected from a group consisting of solder and~~ a conductive adhesive.

5. (ORIGINAL) A method as recited in claim 2, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

6. (CURRENTLY AMENDED) A method as recited in claim 1, wherein ~~the exposed portion of at least one of the conductive layers includes a through-hole, where the conductive material is a rivet extending through the through hole~~ at least one of the conductive layer has a via formed therein, wherein the via is round.

7. (CURRENTLY AMENDED) A method as recited in claim ~~6,~~ ~~wherein the rivet creates a grounding path between a top grounded layer and one or more of the underlying conductive layers~~ 1, wherein at least one of the conductive layer has a via formed therein, wherein the via is cross shaped.

8. (CURRENTLY AMENDED) A method as recited in claim [[6]] 1, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

9. (CURRENTLY AMENDED) A method as recited in claim ~~6,~~ ~~wherein one or more of the conductive layers is~~

~~grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers~~ 1, wherein the conductive material is plated solder.

10. (CURRENTLY AMENDED) A method as recited in claim 1, wherein ~~the conductive material is a finger formed by etching, the finger extending from an uppermost of the conductive layers and pressed onto the exposed portion of an underlying conductive layer~~ the conductive material is screen solder.

11. (CURRENTLY AMENDED) A method as recited in claim ~~10,~~ ~~wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel~~ 1, wherein the conductive material is solder, and further comprising reflowing the solder.

12. (CURRENTLY AMENDED) A method as recited in claim ~~10,~~ ~~wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers~~ 1, wherein at least one of the conductive layers has a stepped back edge.

13. (CURRENTLY AMENDED) A method as recited in claim ~~10,~~ ~~wherein the finger is welded and place~~ 12, wherein the conductive material is applied such that the conductive material overhangs the stepped back edge.

14. (CURRENTLY AMENDED) A method as recited in claim 1, ~~wherein the conductive material is a finger formed by etching, the finger being sandwiched between a mount plate and an arm~~ further comprising exposing the exposed portions of the at least one conductive layer.

15. (CURRENTLY AMENDED) A method as recited in claim ~~14,~~ ~~wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel~~ 1, wherein the conductive layers form part of a lead suspension for suspending an electronic component.

16. (CURRENTLY AMENDED) A method as recited in claim ~~14,~~ ~~wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers~~ 15, wherein the electronic component is a magnetic head.

17. (ORIGINAL) A method as recited in claim 14, wherein the finger is welded in place.

18. (ORIGINAL) A method as recited in claim 1, wherein the conductive material is a finger formed by etching, the finger being sandwiched between a mount plate and a load beam.

19. (ORIGINAL) A method as recited in claim 18, wherein a material of one or more of the conductive layers is

copper and a material of one or more of the conductive layers is stainless steel.

20. (ORIGINAL) A method as recited in claim 18, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

21. (ORIGINAL) A method as recited in claim 18, wherein the finger is welded in place.

22. (ORIGINAL) A method as recited in claim 1, further comprising an extraneous conductive layer, the conductive material being a dimple extending from the extraneous conductive layer and contacting the exposed portions of the conductive layers.

23. (ORIGINAL) A method as recited in claim 22, wherein the dimple extends through a via in at least one of the conductive layers.

24. (ORIGINAL) A method as recited in claim 22, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

25. (ORIGINAL) A method as recited in claim 22, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more

dedicated ground paths etched from one or more of the conductive layers.

26. (ORIGINAL) A method as recited in claim 1, wherein the portions of the conductive layers are exposed by punching a hole through the conductive layers, the conductive material extending through the hole.

27. (ORIGINAL) A method as recited in claim 26, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

28. (ORIGINAL) A method as recited in claim 26, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.